DCR2560A85

Phase Control Thyristor

Preliminary Information

DS5932-1.1 January 2009 (LN 26574)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V_{DRM} and V_{RRM} V	Conditions
DCR2560A85* DCR2560A80 DCR2560A75 DCR2560A70	8500 8000 7500 7000	T_{vj} = -40°C to 125°C, I_{DRM} = I_{RRM} = 300mA, V_{DRM}, V_{RRM} t_p = 10ms, V_{DSM} & V_{RSM} = V_{DRM} & V_{RRM} + 100V respectively

Lower voltage grades available.
*8200V @ -40°C, 8500V @ 0°C

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

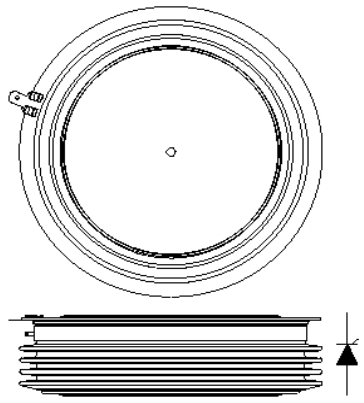
DCR2560A85

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

V_{DRM}	8500V
$I_{T(AV)}$	2560A
I_{TSM}	32500A
dV/dt*	1500V/µs
dI/dt	200A/µs

* **Higher dV/dt selections available**



Outline type code: A

(See Package Details for further information)

Fig. 1 Package outline

CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load	2555	A
$I_{T(RMS)}$	RMS value	-	4013	A
I_T	Continuous (direct) on-state current	-	3710	A

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I_{TSM}	Surge (non-repetitive) on-state current	10ms half sine, T_{case} = 125°C	32.5	kA
I^2t	I^2t for fusing	V_R = 0	5.28	MA^2s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance – junction to case	Double side cooled	DC	-	0.00603	°C/W
		Single side cooled	Anode DC	-	0.01024	°C/W
			Cathode DC	-	0.01467	°C/W
$R_{th(c-h)}$	Thermal resistance – case to heatsink	Clamping force 83.0kN	Double side	-	0.001	°C/W
		(with mounting compound)	Single side	-	0.002	°C/W
T_{vj}	Virtual junction temperature	On-state (conducting)		-	135	°C
		Reverse (blocking)		-	125	°C
T_{stg}	Storage temperature range			-55	125	°C
F_m	Clamping force			74.0	91.0	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I_{RRM}/I_{DRM}	Peak reverse and off-state current	At V_{RRM}/V_{DRM}, T_{case} = 125°C		-	300	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM}, T_j = 125°C, gate open		-	1500	V/µs
dI/dt	Rate of rise of on-state current	From 67% V_{DRM} to 2x $I_{T(AV)}$	Repetitive 50Hz	-	100	A/µs
		Gate source 30V, 10Ω, t_r < 0.5µs, T_j = 125°C	Non-repetitive	-	200	A/µs
$V_{T(TO)}$	Threshold voltage – Low level	500 to 1600A at T_{case} = 125°C		-	0.9	V
	Threshold voltage – High level	1600 to 4000A at T_{case} = 125°C		-	1.18	V
r_T	On-state slope resistance – Low level	500A to 1600A at T_{case} = 125°C		-	0.65	mΩ
	On-state slope resistance – High level	1600A to 4000A at T_{case} = 125°C		-	0.46	mΩ
t_{gd}	Delay time	V_D = 67% V_{DRM}, gate source 30V, 10Ω, t_r = 0.5µs, T_j = 25°C		-	3	µs
t_q	Turn-off time	I_T = 3000A, T_j = 125°C, V_R = 200V, dI/dt = 1A/µs, dV_{DR}/dt = 20V/µs linear			1000	µs
Q_S	Stored charge	I_T = 3000A, T_j = 125°C, dI/dt – 1A/µs, V_{Rpeak} ~5100V, V_R ~ 3400V		5150	7950	µC
I_L	Latching current	T_j = 25°C, V_D = 5V		-	3	A
I_H	Holding current	T_j = 25°C, R_{G-K} = ∞, I_{TM} = 500A, I_T = 5A		-	300	mA

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	V_{DRM} = 5V, T_{case} = 25°C	1.5	V
V_{GD}	Gate non-trigger voltage	At V_{DRM}, T_{case} = 125°C	0.3	V
I_{GT}	Gate trigger current	V_{DRM} = 5V, T_{case} = 25°C	400	mA
I_{GD}	Gate non-trigger current	V_{DRM} = 5V, T_{case} = 25°C	20	mA

CURVES

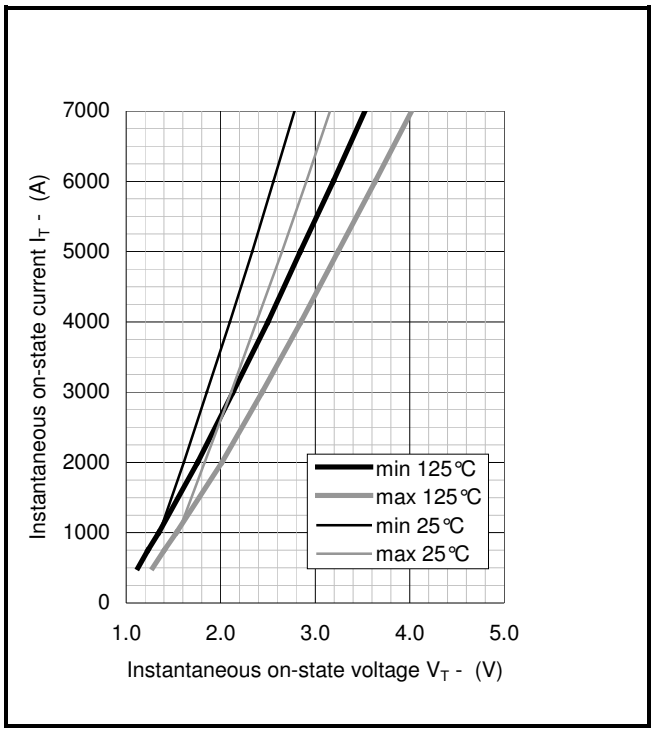


Fig.2 Maximum & minimum on-state characteristics

V_{TM} EQUATION

$V_{TM} = A + B\ln(I_T) + C.I_T + D.\sqrt{I_T}$

Where A = -0.224010
B = 0.1725829
C = 0.000292
D = 0.01039

these values are valid for T_j = 125°C for I_T 500A to 4200A

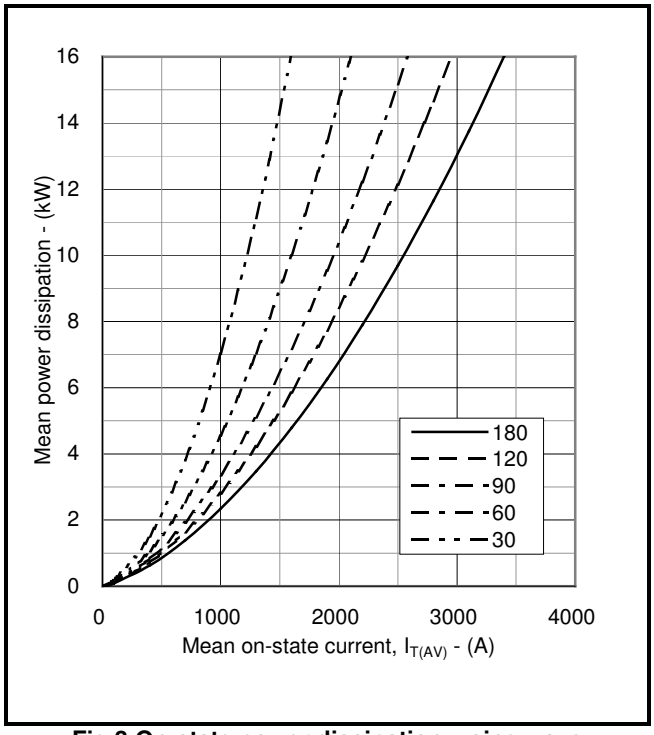


Fig.3 On-state power dissipation – sine wave

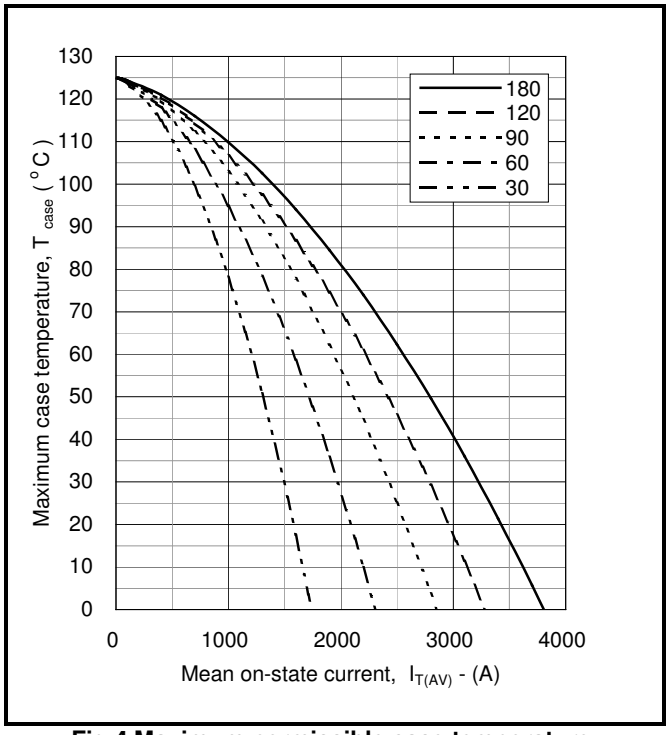


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

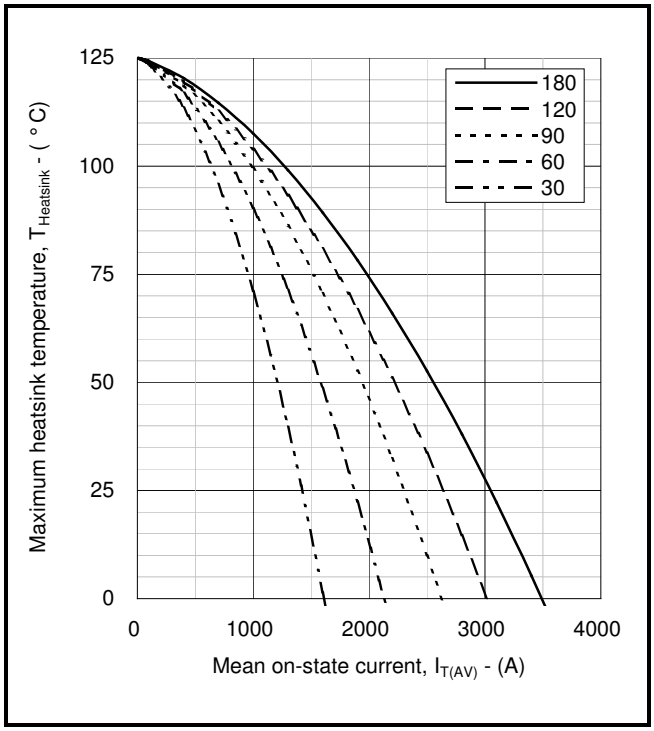


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

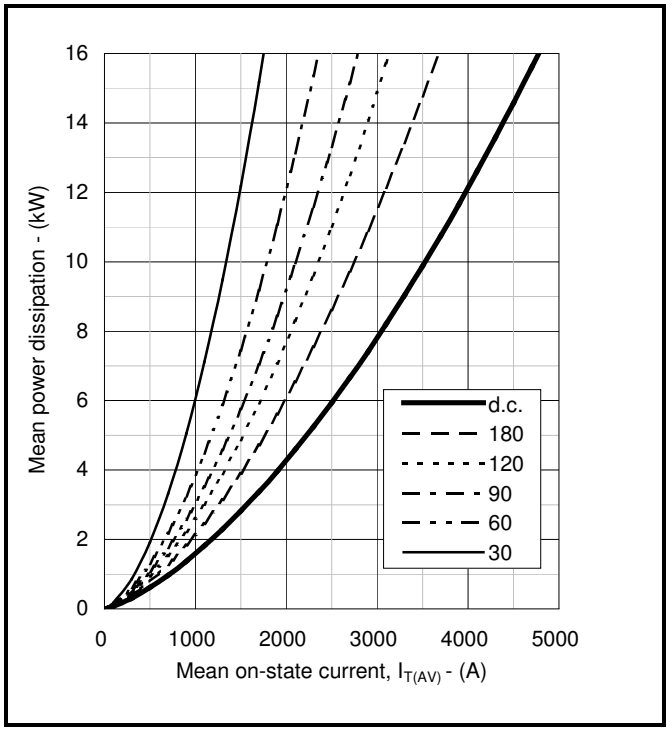


Fig.6 On-state power dissipation – rectangular wave

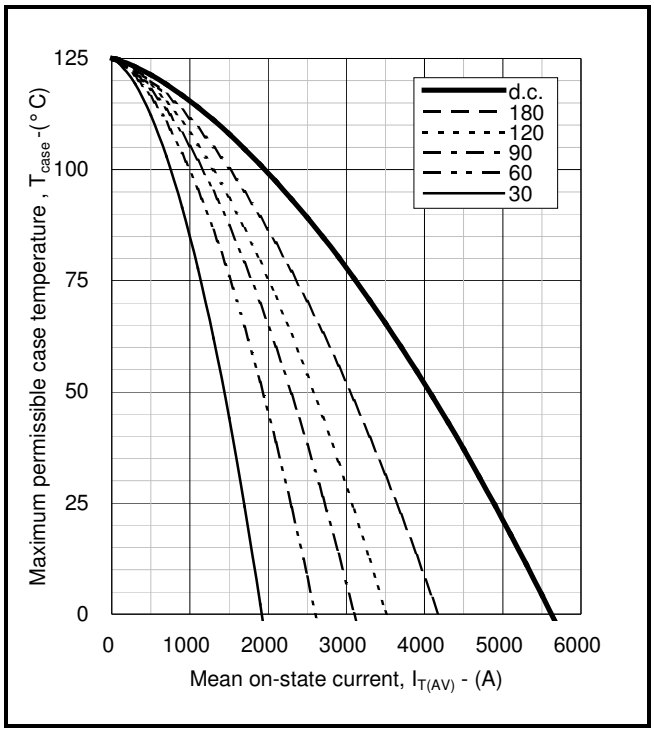


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

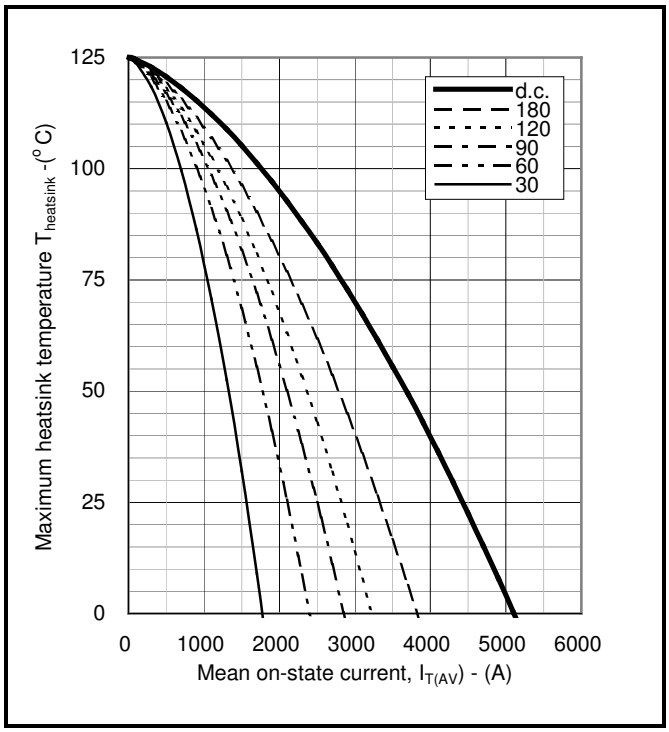
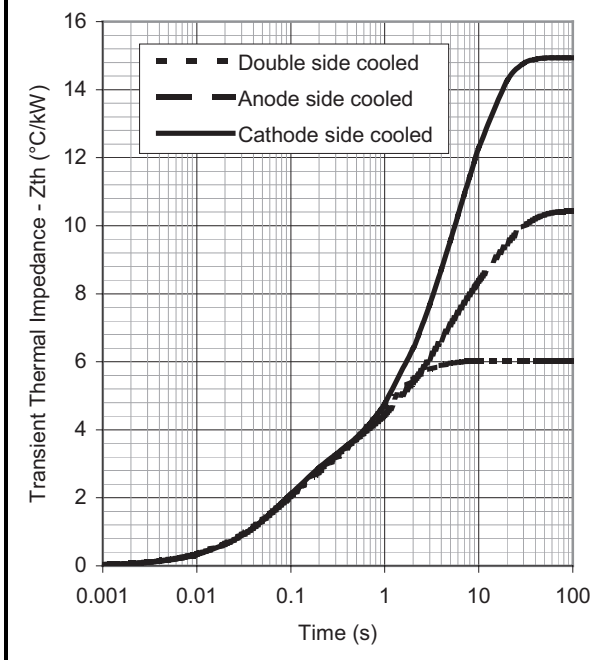


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave



		1	2	3	4
Double side cooled	R_i (°C/kW)	3.01541	1.048955	0.983519	0.983519
	T_i (s)	0.703874	1.904794	0.059	0.059
Anode side cooled	R_i (°C/kW)	3.156003	4.092806	1.556555	1.623962
	T_i (s)	2.69023	13.79162	0.059	0.205916
Cathode side cooled	R_i (°C/kW)	7.077369	3.483481	1.745839	2.634274
	T_i (s)	6.648601	8.436484	1.762119	0.08069

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(T / T_i))]$$

$\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance $R_{th(j-c)}$ when the device operates at conduction angles other than d.c.

Double side cooling		
	ΔZ_{th} (z)	
θ °	sine.	rect.
180	0.44	0.31
120	0.49	0.43
90	0.55	0.49
60	0.60	0.55
30	0.64	0.61
15	0.66	0.64

Anode Side Cooling		
	ΔZ_{th} (z)	
θ °	sine.	rect.
180	0.42	0.30
120	0.47	0.41
90	0.52	0.46
60	0.57	0.52
30	0.61	0.58
15	0.62	0.61

Cathode Sided Cooling		
	ΔZ_{th} (z)	
θ °	sine.	rect.
180	0.42	0.30
120	0.47	0.41
90	0.52	0.46
60	0.57	0.52
30	0.60	0.58
15	0.62	0.60

Fig.9 Maximum (limit) transient thermal impedance – junction to case (°C/kW)

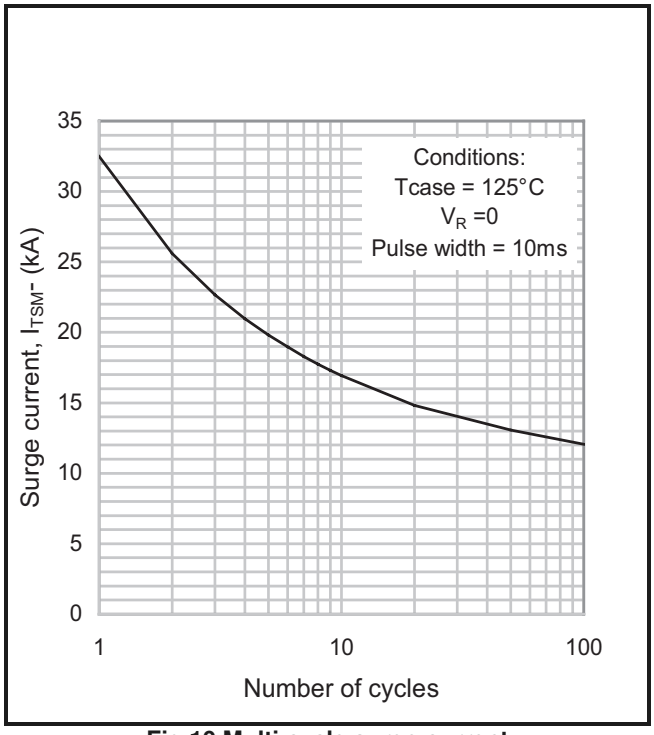


Fig.10 Multi-cycle surge current

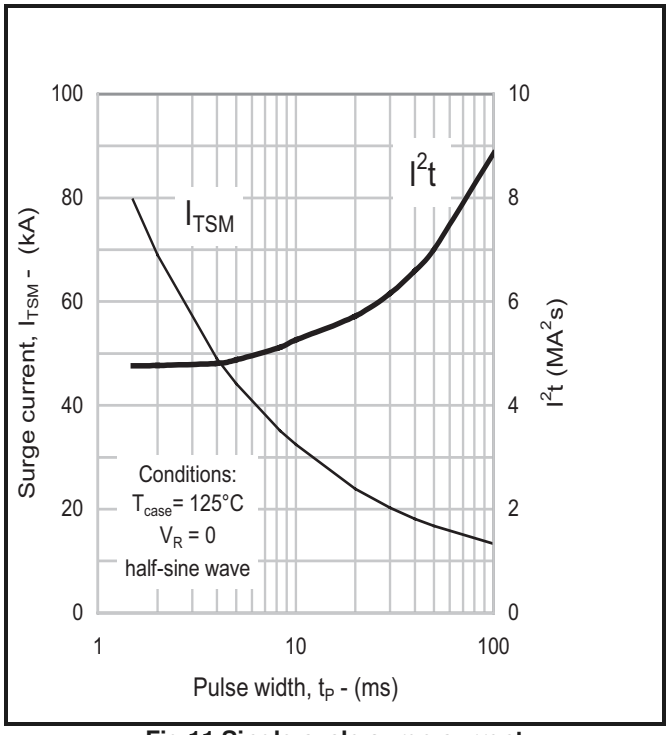


Fig.11 Single-cycle surge current

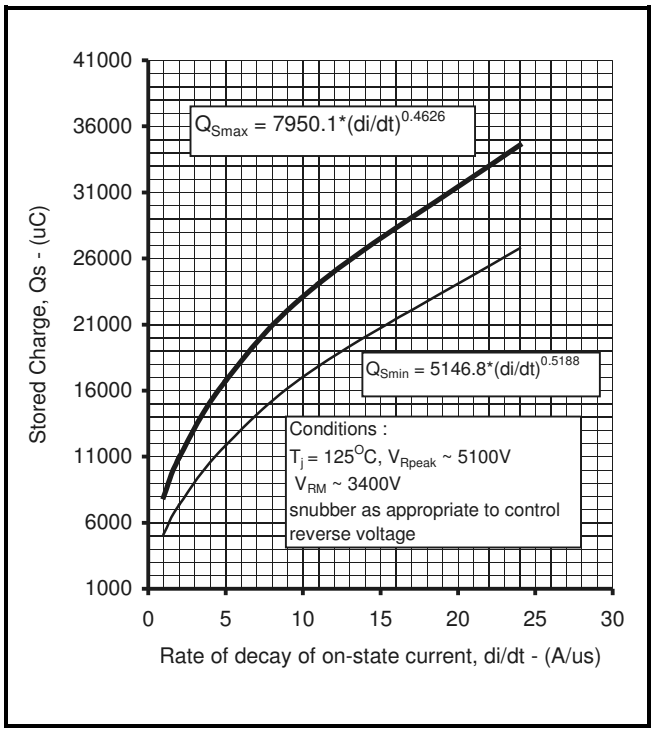


Fig.12 Stored charge

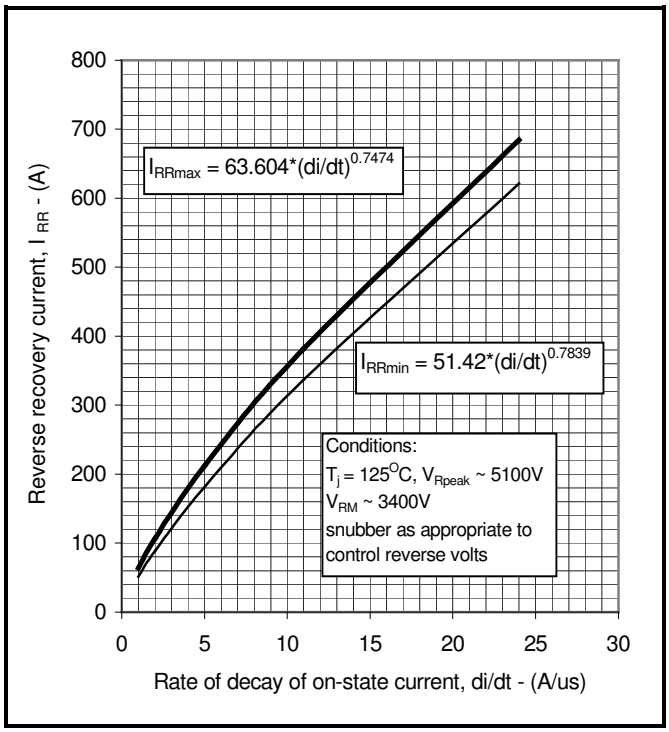


Fig.13 Reverse recovery current

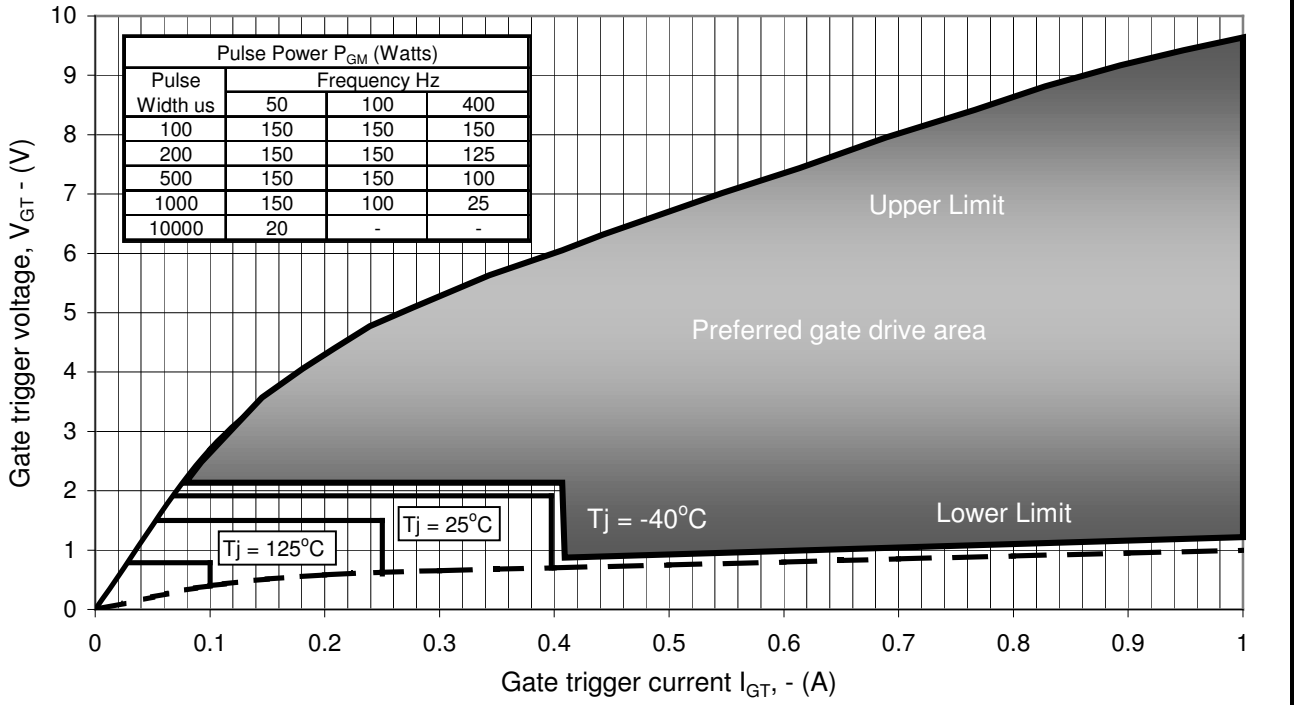


Fig14 Gate Characteristics

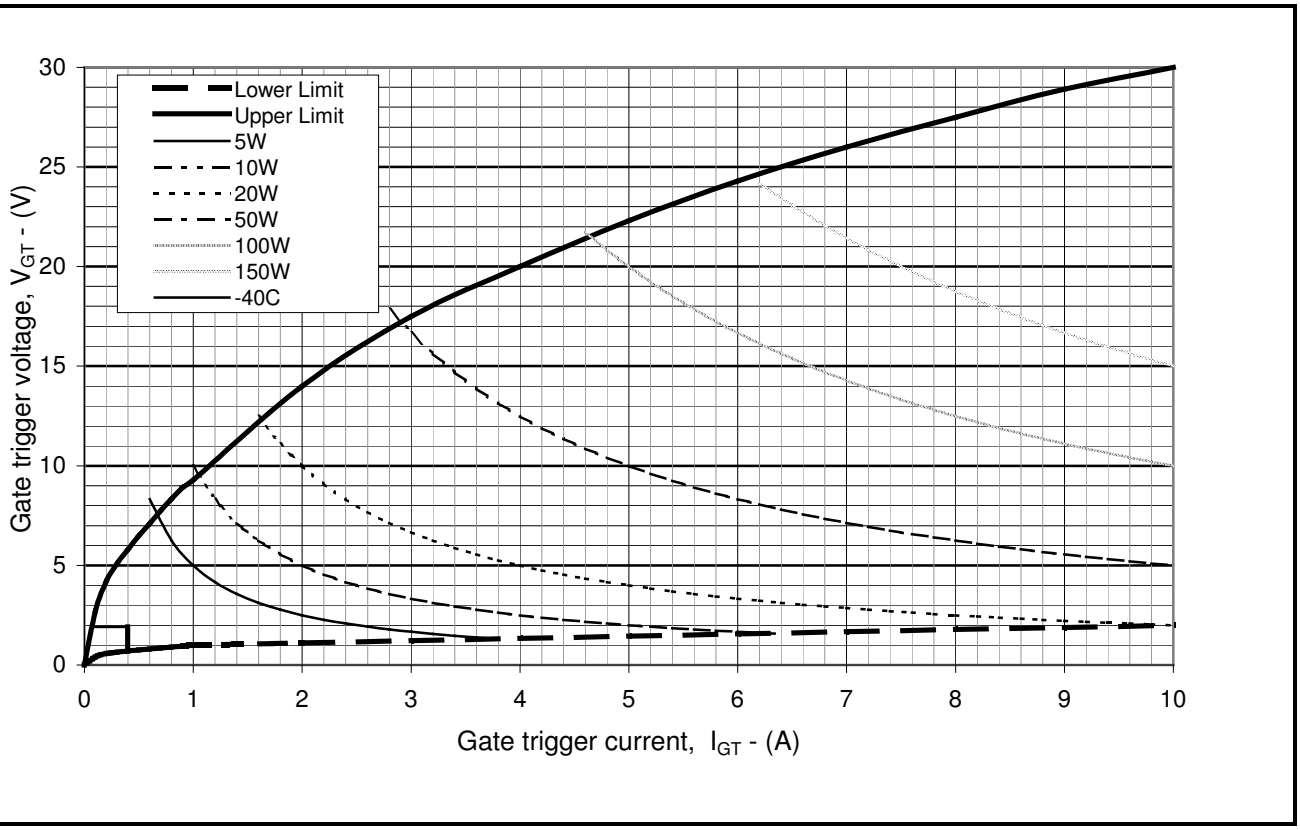
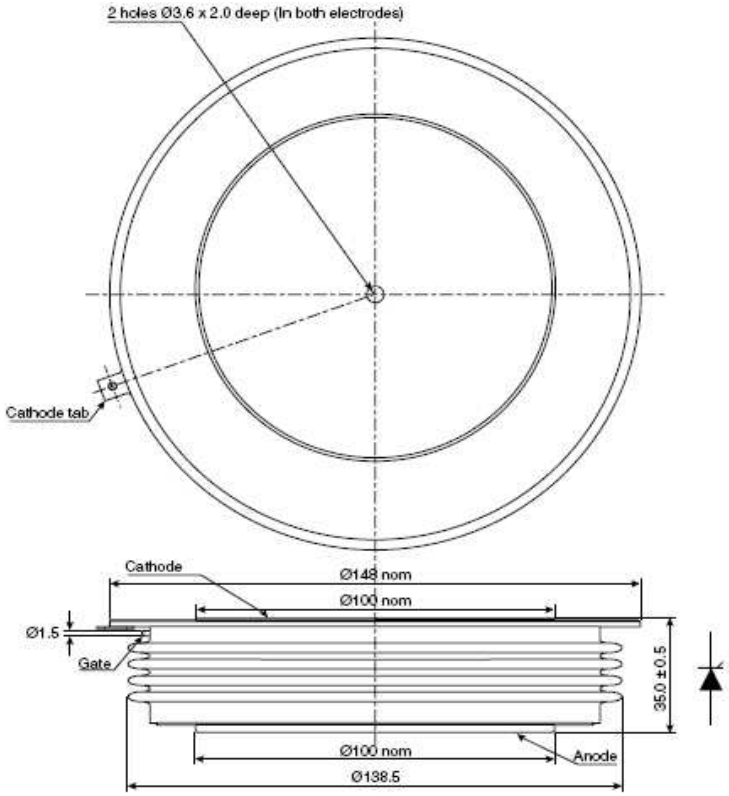


Fig. 15 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Lead length: 420mm
Lead terminal connector: M4 ring

Package outline type code: A

Fig.16 Package outline

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.

http://www.dynexsemi.com

e-mail: power_solutions@dynexsemi.com

HEADQUARTERS OPERATIONS
DYNEX SEMICONDUCTOR LTD
Doddington Road, Lincoln
Lincolnshire, LN6 3LF. United Kingdom.
Tel: +44(0)1522 500500
Fax: +44(0)1522 500550

CUSTOMER SERVICE
Tel: +44(0)1522 502753 / 502901. Fax: +44(0)1522 500020

© Dynex Semiconductor 2003 TECHNICAL DOCUMENTATION – NOT FOR RESALE. PRODUCED IN UNITED KINGDOM.

This publication is issued to provide information only which (unless agreed by the Company in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. The Company reserves the right to alter without prior notice the specification, design or price of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to the Company's conditions of sale, which are available on request.

All brand names and product names used in this publication are trademarks, registered trademarks or trade names of their respective owners.